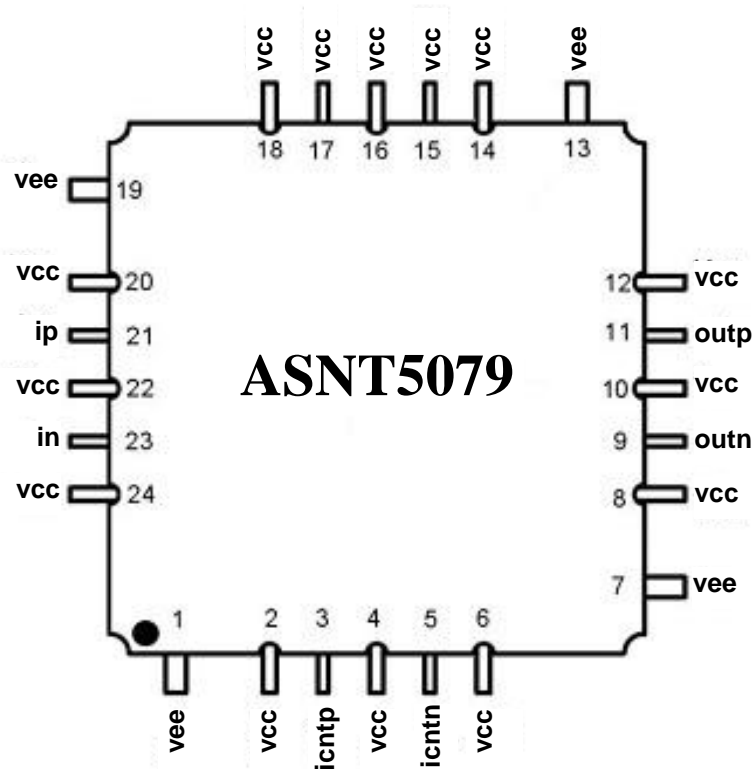




## ASNT5079-KMC DC-20Gbps/14GHz Signal Phase Shifter with Linearized OB

- Broadband (DC-20Gbps/DC-14GHz) tunable data/clock phase shifter
- Delay adjustment range up to 280ps
- Exhibits low jitter and limited temperature variation over industrial temperature range
- 1GHz of bandwidth for the phase adjustment tuning ports
- Ideal for high speed proof-of-concept prototyping
- Fully differential CML input interfaces
- Fully differential CML output interface with 600mV single-ended swing
- Linearized data output for minimized undershoot/overshoot
- Single +3.3V or -3.3V power supply
- Power consumption: 1.6W
- Fabricated in SiGe for high performance, yield, and reliability
- Custom CQFP 24-pin package



## DESCRIPTION

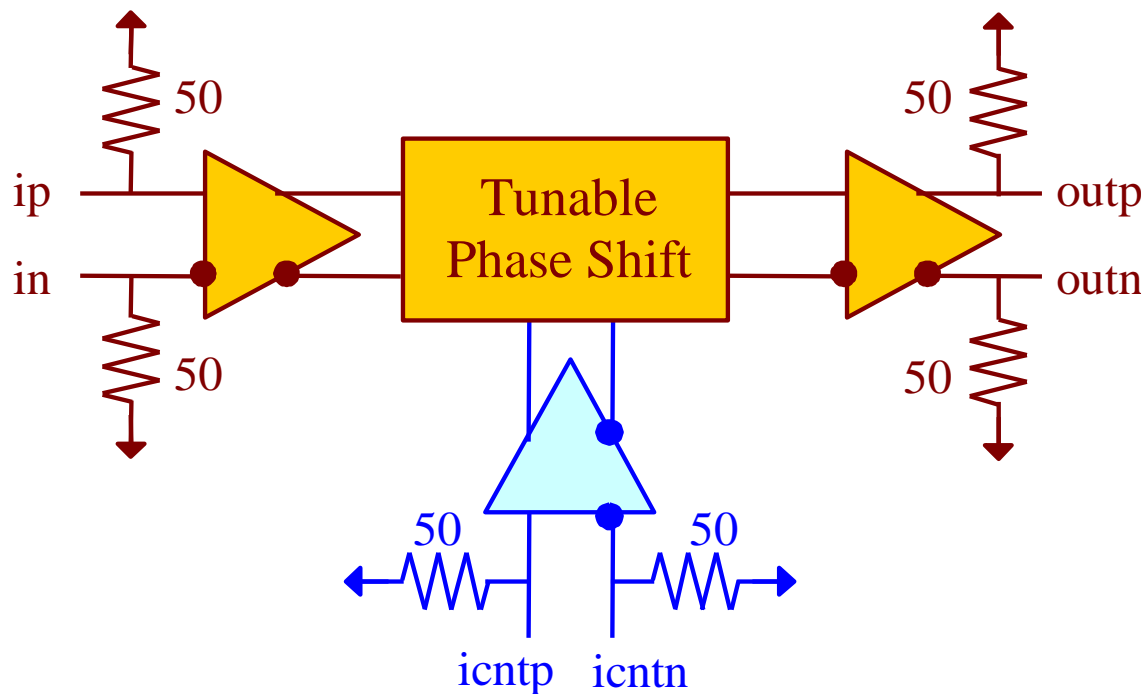


Fig. 1. Functional Block Diagram

ASNT5079-KMC is a data / clock variable delay line fabricated in SiGe technology. The IC shown in Fig. 1 provides an adjustable delay of its differential output signal **outp/outn** in relation to its broadband input signal **ip/in**. The delay adjustment range is temperature-stabilized. The delay is controlled through a wide-band differential tuning port **icntp/icntn**.

The part's I/O's support the CML logic interface with on chip *50Ohms* termination to **vcc** and may be used differentially, AC/DC coupled, single-ended, or in any combination (see also POWER SUPPLY CONFIGURATION). In the DC-coupling mode, the input signal's common mode voltage should comply with the specifications shown in ELECTRICAL CHARACTERISTICS. In the AC-coupling mode, the input termination provides the required common mode voltage automatically. The differential DC signaling mode is recommended for optimal performance.

The output buffer is linearized for reduction of undershoot and overshoot on the output waveforms. Due to an extremely low jitter, the part is suitable for use in high-speed measurement / test equipment.

## Delay Control Port

The delay is controlled through a wide-band differential tuning port **icntp/icntn**. The delay control diagram is shown in Fig. 2.

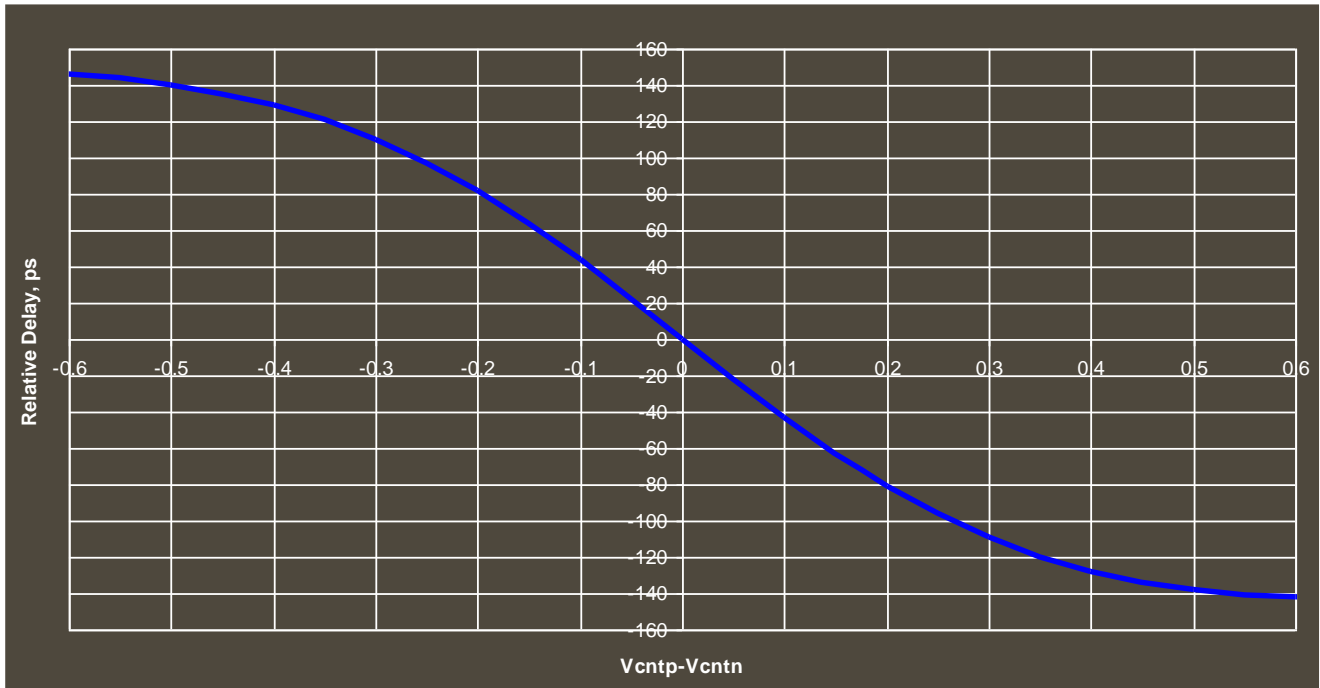


Fig. 2. Delay Control Diagram



## POWER SUPPLY CONFIGURATION

The part can operate with either a negative supply ( $v_{cc} = 0.0V = \text{ground}$  and  $v_{ee} = -3.3V$ ), or a positive supply ( $v_{cc} = +3.3V$  and  $v_{ee} = 0.0V = \text{ground}$ ). In case of a positive supply, all I/Os need AC termination when connected to any devices with  $50\Omega$  termination to ground. Different PCB layouts will be needed for each different power supply combination.

**All the characteristics detailed below assume  $v_{cc} = 0.0V$  and  $v_{ee} = -3.3V$ .**

## ABSOLUTE MAXIMUM RATINGS

Caution: Exceeding the absolute maximum ratings may cause damage to this product and/or lead to reduced reliability. Functional performance is specified over the recommended operating conditions for power supply and temperature only. AC and DC device characteristics at or beyond the absolute maximum ratings are not assumed or implied. All min and max voltage limits are referenced to ground.

Table 1. Absolute Maximum Ratings

Parameter	Min	Max	Units
Supply Voltage ( $v_{ee}$ )		-3.6	V
Power Consumption		1.8	W
RF Input Voltage Swing (SE)		1.0	V
Case Temperature		+90	$^{\circ}C$
Storage Temperature	-40	+100	$^{\circ}C$
Operational Humidity	10	98	%
Storage Humidity	10	98	%

## TERMINAL FUNCTIONS

TERMINAL			DESCRIPTION
Name	No.	Type	
<b>High-Speed I/Os</b>			
ip	21	CML input	Differential high-speed signal inputs with internal SE $50\Omega$ termination to $v_{cc}$
in	23		
icntp	3	CML input	Differential high-speed control inputs with internal SE $50\Omega$ termination to $v_{cc}$
icntn	5		
outp	11	CML output	Differential high-speed signal outputs with internal SE $50\Omega$ termination to $v_{cc}$ . Require external SE $50\Omega$ termination to $v_{cc}$
outn	9		
<b>Supply and Termination Voltages</b>			
Name	Description		Pin Number
vcc	Positive power supply (+3.3V or 0)		2, 4, 6, 8, 10, 12, 14, 15, 16, 17, 18, 20, 22, 24
vee	Negative power supply (0V or -3.3V)		1, 7, 13, 19



## ELECTRICAL CHARACTERISTICS

PARAMETER	MIN	TYP	MAX	UNIT	COMMENTS
<b>General Parameters</b>					
vee	-3.1	-3.3	-3.5	V	±6%
vcc		0.0		V	External ground
I <sub>vee</sub>		485		mA	
Power consumption		1600		mW	
Junction temperature	-40	25	125	°C	
<b>HS Input Data/Clock (ip/in)</b>					
Data Rate	DC		20	Gbps	
Frequency	DC		14	GHz	For clock signals
Swing	0.05		1.0	V	Differential or SE, p-p
CM Voltage Level	vcc-0.8		vcc	V	Must match for both inputs
<b>HS Output Data/Clock (outp/outn)</b>					
Data Rate	DC		20	Gbps	
Frequency	DC		14	GHz	For clock signals
Logic "1" level		vcc		V	
Logic "0" level	vcc-0.6	vcc-0.3	vcc	V	With external 50Ohms DC termination
Rise/Fall times	6		10	ps	20%-80%
Output Jitter			1	ps	Peak-to-peak
Duty cycle	45	50	55	%	For clock signal
<b>Output-to-Input Delay</b>					
Adjustment range		290		ps	For the full range of icntp/icntn control signals
		280		ps	
Absolute delay stability	-3		3	ps	0-125°C
<b>Phase Shift Control port (icntp/icntn)</b>					
Bandwidth	DC		1000	MHz	
SE voltage level	vcc-600		vcc	mV	Half control range when the opposite pin is at vcc
SE voltage level	vcc-1200		vcc	mV	Full control range when the opposite pin is at vcc-0.6V
Differential swing	0		1200	mV	Peak-peak, full control range
CM Level		vcc-(Diff. swing)/4		V	In differential mode



## PACKAGE INFORMATION

The die is housed in a custom 24-pin CQFP package shown in Fig. 3. The package's leads will be trimmed to a length of 1.0mm. After trimming, the package's leads will be further processed as follows:

1. The lead's gold plating will be removed per the following sections of J-STD-001D:
  - 3.9.1 Solderability
  - 3.2.2 Solder Purity Maintenance
  - 3.9.2 Solderability Maintenance
  - 3.9.3 Gold Removal
2. The leads will be tinned with Sn63Pb37 solder

The package provides a center heat slug located on its back side to be used for heat dissipation. ADSANTEC recommends for this section be soldered to the VCC plain, which is ground for a negative supply, or power for a positive supply.

The part's identification label is ASNT5079-KMC. The first 8 characters of the name before the dash identify the bare die including general circuit family, fabrication technology, specific circuit type, and part version while the 3 characters after the dash represent the package's manufacturer, type, and pin out count.

This device complies with Commission Delegated Directive (EU) 2015/863 of 4 June 2015 amending Annex II to Directive 2011/65/EU of the European Parliament and of the Council as regards the list of restricted substances (Text with EEA relevance) on the restriction of the use of certain hazardous substances in electrical and electronics equipment (RoHS Directive) in accordance with the definitions set forth in the directives for all ten substances.

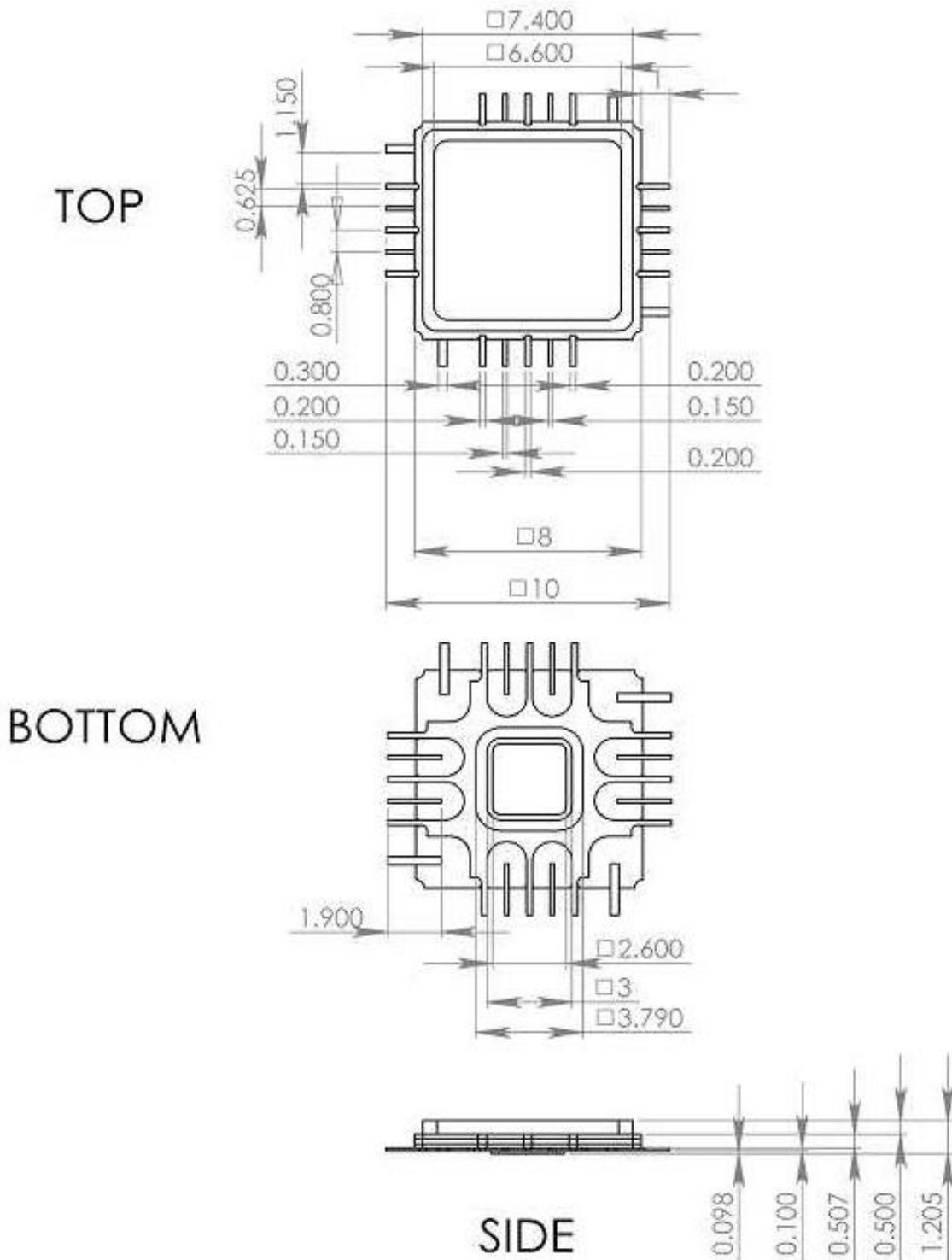


Fig. 3. CQFP 24-Pin Package Drawing (All Dimensions in mm)



## REVISION HISTORY

Revision	Date	Changes
5.4.2	10-2024	Updated Package Information
5.3.2	01-2020	Updated Package Information
5.2.2	07-2019	Updated Letterhead
5.2.1	06-2013	Corrected title Corrected electrical characteristics table
5.1.1	02-2013	Added delay control diagram
5.0.1	02-2013	Added package pin out drawing Revised functional block diagram Added power supply configuration Added absolute maximum ratings Revised terminal functions Revised electrical characteristics Revised package information Added mechanical drawing Format correction
4.0	10-2008	Revised electrical characteristics section Added packaging information section
3.0	06-2007	Revised electrical characteristics section
2.0	04-2007	Revised terminal functions section
1.0	01-2007	First release